

# BENEQ P400A



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## Thermal ALD

- Production proven
- Batch size up to 8m<sup>2</sup>
- Typical dep rate 1–2 μm/24h
- Typical uniformity <2 % over the batch
- Typical materials Al<sub>2</sub>O<sub>3</sub>, TiO<sub>2</sub>, SiO<sub>2</sub>
- Typical substrates:
  - Domes
  - High curvature lenses (dia 1...100 mm)
  - Glass wafer or sheet (coating on both sides)
  - Dies on carrier

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## PROCESS TYPE

- thermal ALD

## USAGE

- production

## SUBSTRATE TYPE

- wafers
- glass and metal sheets
- 3D-parts
- Max substrate size:  
370x470 mm

## SUBSTRATE LOADING

- manual

## MAIN DIMENSIONS

- 2400 × 930 × 2420 mm

## INTEGRATION

- stand-alone

For product inquiries, please contact:

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Technical information in this document is subject to change without notice. 3/2021

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